

smartsystems integration

International Conference and Exhibition
on Integration Issues of Miniaturized Systems

Call for Papers

Dresden, Germany,
11–12 April 2018
smartsystemsintegration.com

Co-organizer:



Part of the activities of:



mesago
Messe Frankfurt Group

Invitation SSI 2018

Currently, we hear and read a lot about digital transformation, which is influencing many aspects of daily lives. "The digital transformation in full swing all round the world. The technological progress is rapid and is changing the way we communicate, work, learn and live. It offers tremendous potential for improving people's quality of life, for doing business more efficiently, and for creating revolutionary business models."* Our world is becoming more and more connected. Thousands, millions, billions of connected devices create a bridge between real and virtual world. Fundamental basis for the internet of things is the integration of hardware, software and connectivity. Smart integrated systems play thereby an important role as they are the hardware basis for a connected world.

The Smart Systems Integration Conference 2018 - as a part of the activities of the European Technology Platform on Smart Systems Integration EPoSS - addresses again all aspects of smart systems, starting from the international research on new materials and technologies, innovative smart systems, their manufacturing technologies, issues of integration up to applications in industry. We will especially continue to present application-oriented topics in the fields smart mobility, smart health, smart energy, smart production and smart society. Additionally, we will address software aspects in connection with smart systems.

On behalf of the committee, the Co-Chair - Dr. G. Lugert of Siemens AG and Chairman of EPoSS Executive Committee – and the local Co-Chairs from Germany – Dr. W. Dettmann (Infineon Technologies AG), Prof. Dr. K. Kabitzsch (Dresden University of Technology), C. Kögler (T-Systems Multimedia Solutions GmbH and Silicon Saxony e. V.) and Prof. K.-D. Lang (Fraunhofer IZM) – I am looking forward to receiving your application or scientific oriented submission.

* White Paper of Digital Platforms of Federal Ministry for Economic Affairs and Energy



Prof. Dr. T. Otto

Fraunhofer Institute for Electronic Nano Systems
Conference Chair Smart Systems Integration 2018

Conference topics 2018

- A. Applications**
 - A01 Smart mobility
 - A02 Smart health
 - A03 Smart energy
 - A04 Smart society
 - A05 Smart production
- B. Hardware/Technologies**
 - B01 Design of smart integrated systems
 - B02 Manufacturing of embedded micro and nano systems
 - B03 Advanced micro and nano technologies
 - B04 New materials for nano structures and devices
 - B05 Smart low cost approaches including Roll-to-Roll technologies and printed functionalities
 - B06 Smart test and reliability of components and systems
 - B07 System integration: 3D integration, interconnect technologies and packaging
- C. Software for smart integrated systems**
 - C01 Embedded software
 - C02 Distributed embedded systems
 - C03 Self-X systems (learning, organising, optimising, repairing ...)
 - C04 Methods of software life cycle (design, test, commissioning ...)
- D. Business creation of Smart Systems**
 - D01 Market Trends
 - D02 Perspectives of Smart Systems
 - D03 Ecosystems for Smart Solutions
 - D04 SME success stories


Smart Systems Integration International Conference and Exhibition

- Focuses on complex systems in consideration of the components,
- Is application-oriented,
- Close to the industry and
- Shows the potential of research and development activities worldwide.

Become a speaker!

**Highlight your expertise
at the SSI conference with
concurrent exhibition!**

Your advantages

- Present your knowledge in front of a highly qualified audience.
- Exchange your experience with other international experts from all over Europe.
- Enjoy the conference dinner on a paddle steamer with an adventure river cruise on the Elbe.
- Publish your paper in the Smart Systems Integration proceedings with ISBN.
- Publish your presentation in the online and printed conference program.
- Benefit from maximum attention for your presentation due to extensive press work and advertising activities.
- Take the opportunity to win the Best Paper or Best Poster Award. 
- Invite your colleagues and business partners with special conference prices.

**Online submission until 5 October 2017
at smartsystemsintegration.com**

The conference committee decides about acceptance of the submission.



Contact for further details
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Submission requirements

Conference language

English

Conditions of acceptance

Authors are expected to secure the registration fee of 325 EUR + VAT as well as travel and accommodation funding through their sponsoring organizations, before submitting abstracts. Full payment will be due once the submission has been accepted. Only original material should be submitted. Government and company clearance to present and publish should be finalized at the time of submission. Non-research based papers which attempt to promote commercial products cannot be submitted.

Selection process

The committee will review all submitted abstracts to maintain the high quality of the conference. Only papers submitted on time and addressing subjects which are topical and relevant to the conference will be considered for inclusion in the conference programme. Submitted papers may be selected for oral or poster presentations.

»The SSI is a very good platform to get news about future MEMS applications and trends in process technologies. A lot of information are available within the two days of the conference. It is also a great event for networking between research and development organizations and the industry.«

Uwe Schwarz, MEMS Process Development, X-FAB MEMS Foundry GmbH

Oral and poster presentations

Oral presentations will be held in different sessions. The duration of each presentation should not exceed 25 minutes including 5 minutes for subsequent discussions. Poster authors will have the opportunity to present their posters during a special poster session and throughout the conference. All oral and poster presentations will be included in the conference proceedings.

Deadlines

Submission of abstracts

5 October 2017

Selection by committee

9 November 2017

Submission of full manuscripts

28 February 2018

Submission no later than 5 October 2017
at smartsystemintegration.com/callforpapers

Impressions of SSI 2017
Exhibition and conference in Cork, Ireland

